

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUAN WANG	05/29/2014
HEJIN LIU	05/29/2014
WEIPING SUN	05/29/2014
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City:	Austin
State/Country:	TEXAS
Postal Code:	78735
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14554064
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NAME OF SUBMITTER:	CASSIE YE
SIGNATURE:	/Cassie Ye/
DATE SIGNED:	11/26/2014
Total Attachments: 4	
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PATENT

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **HUAN WANG, HEJIN LIU AND WEIPING SUN, ALL OF CHINA**, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto **FREESCALE SEMICONDUCTOR, INC.**, a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in **SEMICONDUCTOR DEVICE ASSEMBLED USING TWO LEAD FRAMES** (Docket No. **MF10298AK**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by us on the dates indicated by our signatures below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto **FREESCALE SEMICONDUCTOR, INC.**, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and we further authorize **FREESCALE SEMICONDUCTOR, INC.** to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to **FREESCALE SEMICONDUCTOR, INC.**, for the sole use and benefit of **FREESCALE SEMICONDUCTOR, INC.**, its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to **FREESCALE SEMICONDUCTOR, INC.**

We agree that, when requested, we will, without charge to **FREESCALE SEMICONDUCTOR, INC.**, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the

inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

HUAN WANG
 HUAN WANG

DATE: May - 29 - 2014

First Witness

Wang Yang
 SIGNATURE OF WITNESS

DATE: May - 29 - 2014
 (Month-Day-Year)

Wang Yang
 PRINTED NAME OF WITNESS

天津市北辰区
 PRINTED ADDRESS OF WITNESS

Second Witness

Bai Lianping
 SIGNATURE OF WITNESS

DATE: May - 29 - 2014
 (Month-Day-Year)

Bai Lianping
 PRINTED NAME OF WITNESS

天津市东丽区
 PRINTED ADDRESS OF WITNESS

HEJIN LIU
HEJIN LIU

DATE: May-29-2014

First Witness

Wang Yang
SIGNATURE OF WITNESS

DATE: May-29-2014
(Month-Day-Year)

Wang Yang
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天津市北辰区
PRINTED ADDRESS OF WITNESS

Second Witness

Bai Lanping
SIGNATURE OF WITNESS

DATE: May-29-2014
(Month-Day-Year)

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PRINTED ADDRESS OF WITNESS

WEIPING SUN

WEIPING SUN

DATE: May - 29 - 2014First WitnessWang Yang

SIGNATURE OF WITNESS

DATE: May - 29 - 2014
(Month-Day-Year)Wang Yang

PRINTED NAME OF WITNESS

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DATE: May - 29 - 2014
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